Contact Name Title - Contact Product-Env-Stewards Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company unique ID Unique ID Authority Response Date* 2023-06-08 2023-06-0	752-21.1											als and M	fg Informati	ion	
Semi Filt Contact Phone Contact Product Env-Stewards Onsemi.com Contact Phone Representative Representative Phone Representative Representative Phone Representative Representative Phone Representative Repre	upplier Informa	ation													
Title - Contact Name Product Envis Compliance NA Product Envis Email - Contact* Product-Env-Stewards Pr	Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
Product Env-Stewards uthorized Representative* Title - Representative Product Enviro Compliance NA Product-Env-Stewards Product-Env-Ste	nsemi											2023-06-08			
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Numbe	ontact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envi-Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit Unit Unit Version Manufacturing Site Weight* Version Manufacturing Site Weight* UOM Unit Unit Version Manufacturing Site Weight* Weight* Version Manufacturing Site Weight* Weight* Version Manufacturing Site Weight* Weight* Weight* Version Manufacturing Site Weight* Weight* Weight* Version Manufacturing Site Weight* Weight* Weight* Weight* Version Manufacturing Site Weight* Weight* Weight* Weight* Weight* Version Manufacturing Site Weight* Weigh	Product-Env-Stewar	rds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represen	ntative*	Title - Representative			I	Phone - Representative*			Email - Representative*					
H11D3SR2M 6PW HVCEO TR T&R 2023-06-08 LITEONFG 464.903 mg Each	Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Manufacturing Site		Weight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Comments			H11D3SF	R2M	6PW HVCEO TR T	Γ&R		2023-06-08		L	ITEONFG	4	164.903	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				arminal Rasa	Alloy	STD 020 MSI	Pating	Dank Proc	ace Rody Te	mparatur	May Time at Peak	Tamparat	ura Numb	per of Paflow Cyc	Jac
omments				-		31D-020 MSL	Z Katilig							bei of Kellow Cyc	les
	•	(Sii) - aimeaieu	C	O Alloy	1			1200		<u> </u> C	30	secon	us 3		
ver 1 - maximum time at peak temperature during soldering is 10-50 seconds		me at neak temperature	during cal	doring is 10.3	20 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this f											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	0.4	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.04	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		0.36	mg
Die	5.13	mg	Supplier	Silicon (Si)	7440-21-3		5.13	mg
Die Attach	0.3	mg	Supplier	Silver (Ag)	7440-22-4		0.225	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.075	mg
Lead Frame	101.703	mg	Supplier	Silver (Ag)	7440-22-4		0.407	mg
			Supplier	Zinc (Zn)	7440-66-6		0.203	mg
			Supplier	Iron (Fe)	7439-89-6		2.64	mg
			Supplier	Copper (Cu)	7440-50-8		98.3	mg
			Supplier	Phosphorus (P)	7723-14-0		0.153	mg
Mold Compound-White	327.22	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		81.805	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		9.8166	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		44.1747	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		9.8166	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		163.61	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		17.9971	mg
Plating	28.5	mg	Supplier	Tin (Sn)	7440-31-5		28.5	mg
Wire Bond - Au	1.65	mg	Supplier	Gold (Au)	7440-57-5		1.65	mg